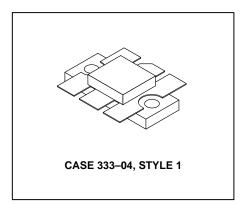
The RF Line NPN Silicon RF Power Transistor

... designed primarily for wideband large-signal output and driver amplifier stages in the 100 to 500 MHz frequency range.

- Specified 28 Volt, 400 MHz Characteristics —
 Output Power = 100 Watts
 Minimum Gain = 7.0 dB
 Efficiency = 50% (Min)
- Built–In Matching Network for Broadband Operation Using Double Match Technique
- 100% Tested for Load Mismatch at all Phase Angles with 3:1 VSWR
- Gold Metallization System for High Reliability

MRF329

100 W, 100 to 500 MHz CONTROLLED "Q" BROADBAND RF POWER TRANSISTOR NPN SILICON



MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	30	Vdc
Collector–Base Voltage	VCBO	60	Vdc
Emitter-Base Voltage	V _{EBO}	4.0	Vdc
Collector Current — Continuous — Peak	IC	9.0 12	Adc
Total Device Dissipation @ T _C = 25°C (1) Derate above 25°C	PD	270 1.54	Watts W/°C
Storage Temperature Range	T _{stg}	-65 to +150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case (2)	$R_{\theta JC}$	0.65	°C/W

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector–Emitter Breakdown Voltage (I _C = 80 mAdc, I _B = 0)	V(BR)CEO	30	_	_	Vdc
Collector–Emitter Breakdown Voltage (I _C = 80 mAdc, V _{BE} = 0)	V(BR)CES	60	_	_	Vdc
Emitter–Base Breakdown Voltage (IE = 8.0 mAdc, IC = 0)	V(BR)EBO	4.0	_	_	Vdc

NOTES:

(continued)

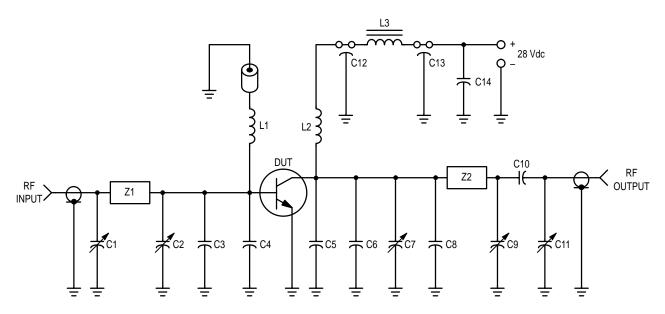
- 1. This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF amplifier.
- 2. Thermal Resistance is determined under specified RF operating conditions by infrared measurement techniques.

REV 6



ELECTRICAL CHARACTERISTICS — **continued** $(T_C = 25^{\circ}C)$ unless otherwise noted.)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS (continued)	•				
Collector–Base Breakdown Voltage (IC = 80 mAdc, IE = 0)	V(BR)CBO	60	_	_	Vdc
Collector Cutoff Current (V _{CB} = 30 Vdc, I _E = 0)	ICBO	_	_	5.0	mAdc
ON CHARACTERISTICS	•				
DC Current Gain (I _C = 4.0 Adc, V _{CE} = 5.0 Vdc)	hFE	20	_	80	_
DYNAMIC CHARACTERISTICS	•			•	
Output Capacitance (V _{CB} = 28 Vdc, I _E = 0, f = 1.0 MHz)	C _{ob}	_	95	125	pF
FUNCTIONAL TESTS (Figure 1)	•			•	
Common–Emitter Amplifier Power Gain (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 400 MHz)	GPE	7.0	9.7	_	dB
Collector Efficiency (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 400 MHz)	η	50	60	_	%
Load Mismatch (V _{CC} = 28 Vdc, P _{out} = 100 W, f = 400 MHz, VSWR = 3:1 all angles)	Ψ	No Degradation in Output Power			



C1, C2, C7, C9 — 1.0-20 pF Johanson (JMC 5501)

C3, C4 — 36 pF 100 mil Chip Cap (ATC)

C5, C6 — 50 pF 100 mil Chip Cap (ATC)

C8 — 30 pF 100 mil Chip Cap (ATC)

C10 — 2.0-150 pF 100 mil Chip Caps in Parallel (ATC)

C11 — 1.0-10 pF Johanson (JMC 5201)

C12, C13 — 1000 pF UNELCO Feedthru

C14 — 0.1 μF Erie Redcap

L1 — 0.15 μ H Molded Choke with Ferrite Bead (Ferroxcube #56–590–65/4B) on Ground End

L2 — 4 Turns #18 AWG, 1/4" ID

L3 — Ferroxcube VK200-19/4B

Z1 — Microstrip Line 2300 mils L x 210 mils W

Z2 — Microstrip Line 2300 mils L x 280 mils W

Board — Glass Teflon, t = 0.062", ϵ_{Γ} = 2.56

Figure 1. 400 MHz Test Circuit

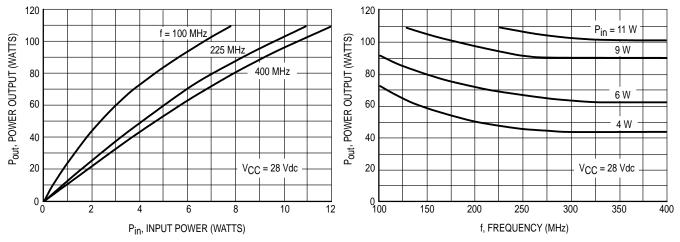


Figure 2. Output Power versus Input Power

Figure 3. Output Power versus Frequency

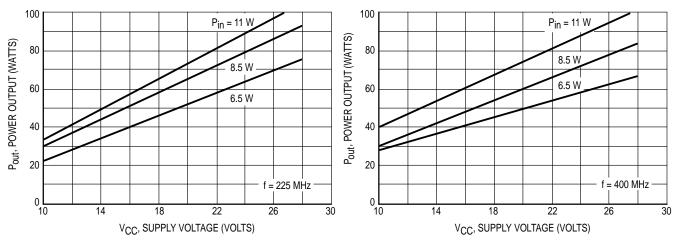


Figure 4. Output Power versus Supply Voltage

Figure 5. Output Power versus Supply Voltage

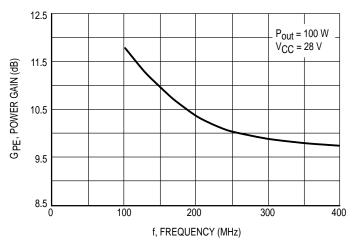
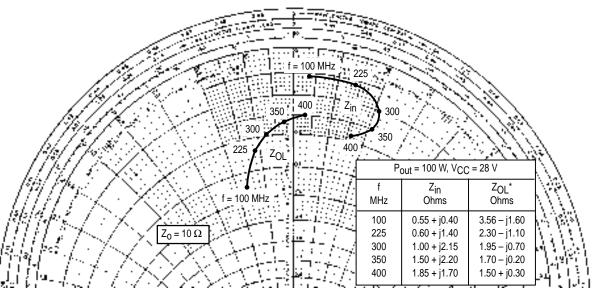


Figure 6. Power Gain versus Frequency

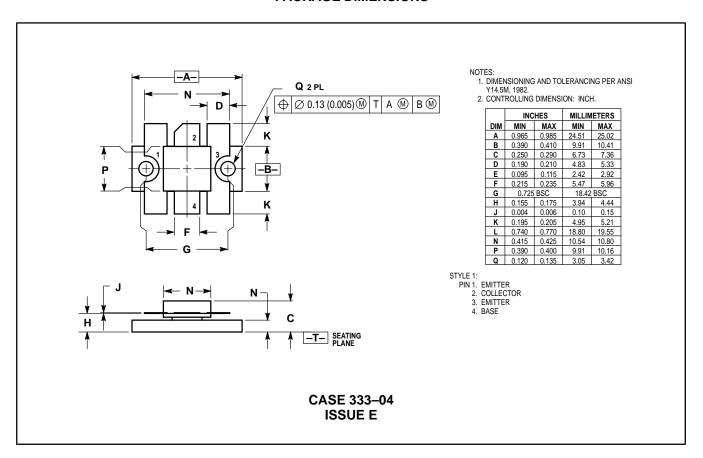
MOTOROLA RF DEVICE DATA MRF329



 Z_{OL}^* = Conjugate of the optimum load impedance into which the device output operates at a given output power, voltage and frequency.

Figure 7. Series Equivalent Input/Output Impedance

PACKAGE DIMENSIONS



MOTOROLA RF DEVICE DATA

MRF329

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